

## N-Channel Trench MOSFET, 60V, 38A, 21mΩ

### General Description

The VAS06R0210DP utilizes the advanced Trench technology and low resistance package to achieve extremely low on-resistance device which makes the system design an efficient and reliable solution for use in a wide variety of applications.

### Features

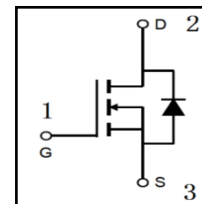
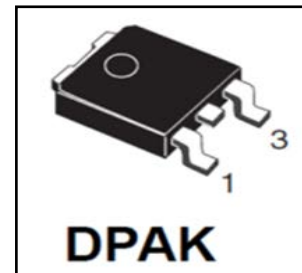
- 60V, 38A,  $R_{DS(on)}=21m\Omega@V_{gs}=10V$
- High Efficiency
- Improved dv/dt, di/dt capability
- 100% EAS Guaranteed
- Green Device

### Application

Motor Drive, Power Tools  
LED Lighting

### Product Summary

$V_{DS}@T_{j,max}$	60 V
$R_{DS(on)}@V_{GS}=10V$	21 mΩ
$I_D$ Continuous Current	38 A
$V_{(GS)th}$	1.8 V
$Q_{g,typ}$	28 nC



### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	Condition
Drain-Source Voltage	$V_{DS}$	60	V	
Continuous drain current <sup>(1)</sup>	$I_D$	38 24	A	$T_C=25^\circ C$ $T_C=100^\circ C$
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	Static
Pulsed drain current <sup>(2)</sup>	$I_{DM}$	152	A	$T_C=25^\circ C$
Avalanche energy, single pulse	$E_{AS}$	42	mJ	$I_D=29A$ ; $V_{DD}=25V$ ; see Figure 9
Avalanche current, single pulse	$I_{AS}$	29	A	$T_C=25^\circ C$
Power dissipation	$P_{diss}$	63	W	$T_C=25^\circ C$
Power dissipation-Derate above 25°C	$P_{derate}$	0.5	W/°C	$T_C=25^\circ C$
Continuous diode forward current	$I_S$	38	A	$T_C=25^\circ C$
Diode pulse current <sup>(2)</sup>	$I_{S,pulse}$	152	A	$T_C=25^\circ C$

(1) Limited by  $T_{j,max}$ .

(2) Pulse width  $T_P$  limited by  $T_{j,max}$



### Thermal characteristics

Symbol	Parameter	Min	Typ	Max	Unit
$R_{thJC}$	Thermal resistance, junction-case, max	---	---	2	°C/W
$R_{thJA}$	Thermal resistance, junction-ambient, max	---	---	62	°C/W
$T_{sold}$	Soldering temperature, max	---	---	260	°C

### Package and Ordering Information

Device	Package	Marking
VAS06R0210DP	TO252	VAS06R0210DP



**Electrical Characteristics** ( $T_j=25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
<b>Static Characteristic</b>						
Drain-Source breakdown Voltage	$V_{(BR)DSS}$	60	---	---	V	$V_{GS}=0V, I_D=0.25mA$
Gate Threshold Voltage	$V_{(GS)th}$	1.2	1.8	2.5	V	$V_{DS}=V_{GS}, I_D=0.25mA$
Drain-Source on resistance	$R_{(DS)on}$	---	17	21	$m\Omega$	$V_{GS}=10V, I_D=20A, T_j=25^\circ\text{C}$
		---	20	24	$m\Omega$	$V_{GS}=4.5V, I_D=12A, T_j=25^\circ\text{C}$
Zero gate voltage drain current	$I_{DSS}$	---	---	1	$\mu A$	$V_{DS}=60V, V_{GS}=0V, T_j=25^\circ\text{C}$
		---	---	10	$\mu A$	$V_{DS}=48V, V_{GS}=0V, T_j=125^\circ\text{C}$
Gate-Source leakage current	$I_{GSS}$	---	---	100	nA	$V_{GS}=20V, V_{DS}=0V$
<b>Dynamic Characteristic</b>						
Input Capacitance	$C_{iss}$	---	1680	2440	pF	$V_{GS}=0V, V_{DS}=25V, f=1MHz$
Output Capacitance	$C_{oss}$	---	115	170	pF	$V_{GS}=0V, V_{DS}=25V, f=1MHz$
Turn-on delay time	$T_{d(on)}$	---	7.2	14	nS	$V_{DD}=30V, V_{GS}=10V, I_D=1A, R_G=6\Omega;$ See Figure 10
Rise time	$T_r$	---	38	72	nS	
Turn-off delay time	$T_{d(off)}$	---	34	65	nS	
Fall time	$T_f$	---	8.2	16	nS	
<b>Gate Charge Characteristic</b>						
Gate to source charge	$Q_{gs}$	---	3.5	7	nC	$V_{DD}=30V, I_D=15A, V_{GS}=10V$
Gate to drain charge	$Q_{gd}$	---	6.5	10	nC	
Gate charge total	$Q_g$	---	28	42	nC	
<b>Reverse diode characteristic</b>						
Diode forward voltage	$V_{FD}$	---	0.7	1	V	$V_{GS}=0V, I_F=1A, T_j=25^\circ\text{C}$
Continuous Source Current	$I_{csc}$	---	---	38	A	$V_G=V_D=0V, \text{Force current}$
Pulsed Source Current	$I_{sm}$	---	---	152	A	
Reverse Recovery Time	$t_{rr}$	---	19.6	---	nS	$V_{GS}=0V, I_{csc}=-1A, di/dt=100A/\mu S,$
Reverse Recovery Charge	$Q_{rr}$	---	14.2	---	nC	$T_j=25^\circ\text{C}$

## Electrical Characteristic Diagrams

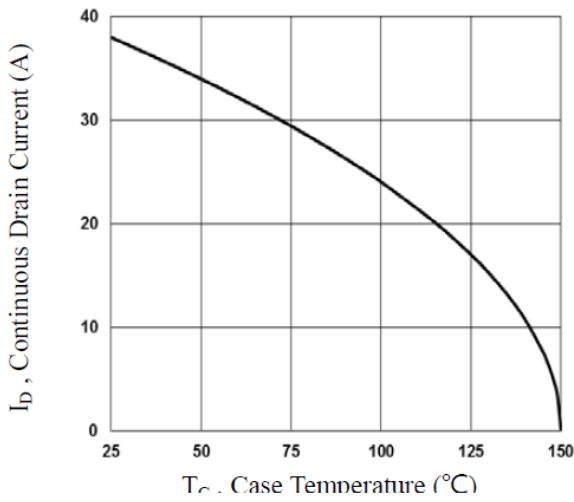


Figure 1 Continuous Drain Current vs. Tc

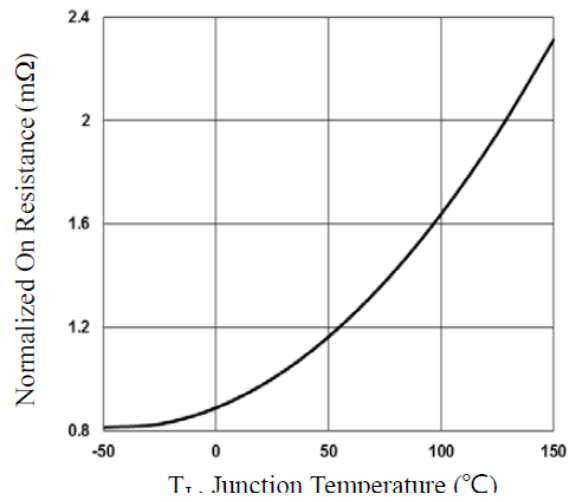


Figure 2 Normalized  $R_{DS(on)}$  vs. Tj

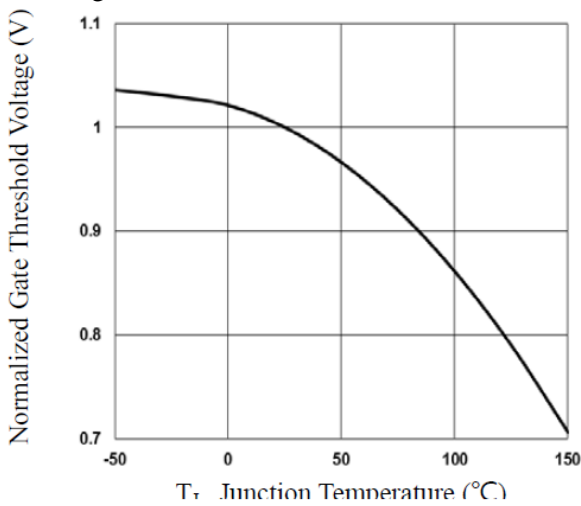


Figure 3 Normalized  $V_{th}$  vs. Tj

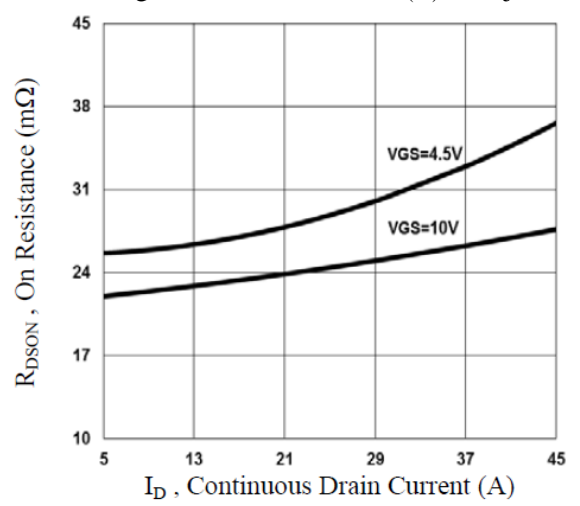


Figure 4  $R_{DS(on)}$  vs. Continuous Current

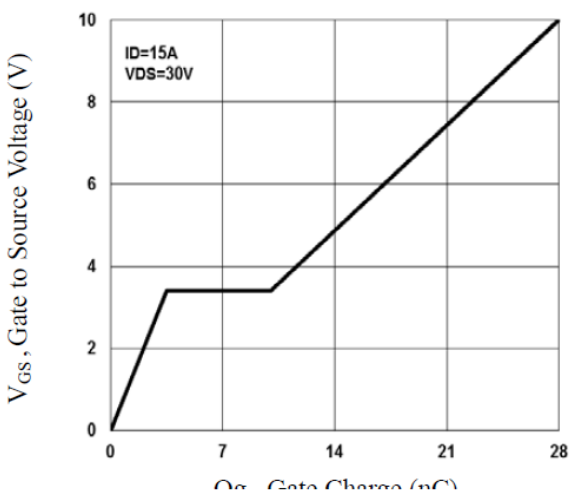


Figure 5 Gate Charge Waveform

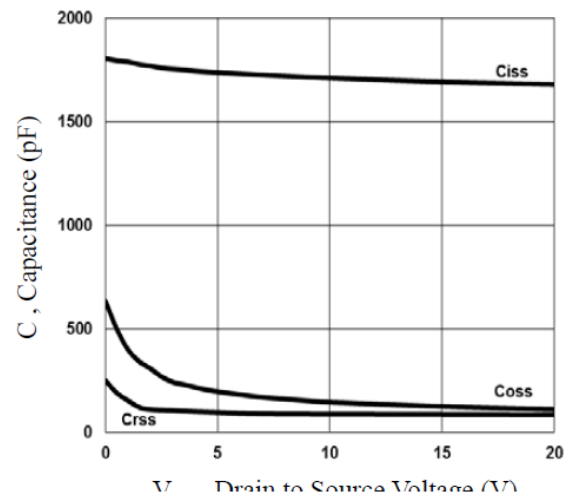


Figure 6 Capacitance Characteristic

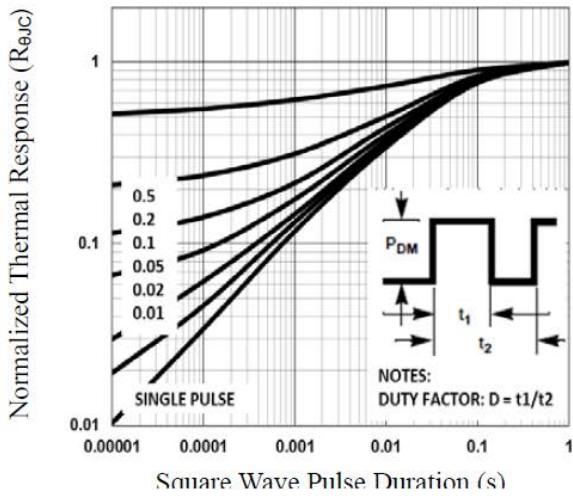


Figure 7 Normalized Thermal Impedance

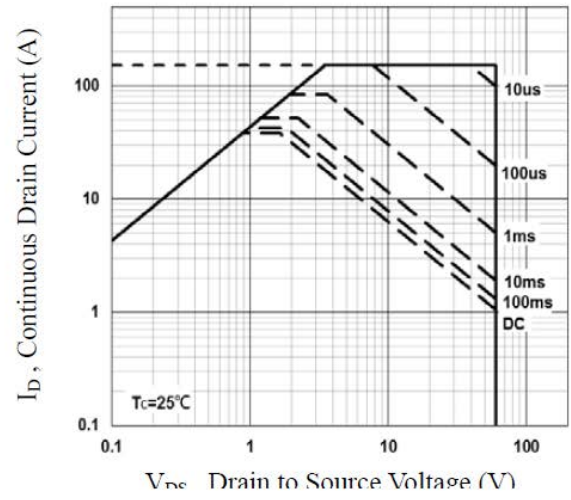


Figure 8 Safe Operating Area

## Parameter Test Circuits

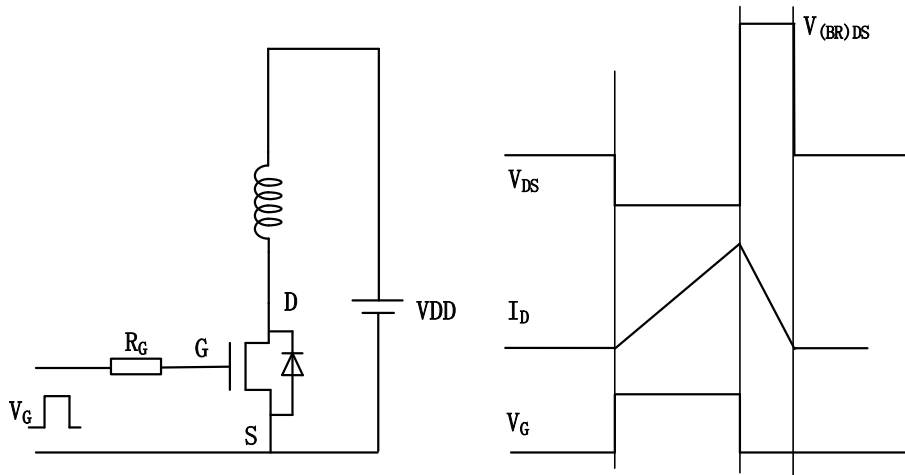


Figure 9 Unclamped Inductive Switching (UIS) Test circuit and waveforms

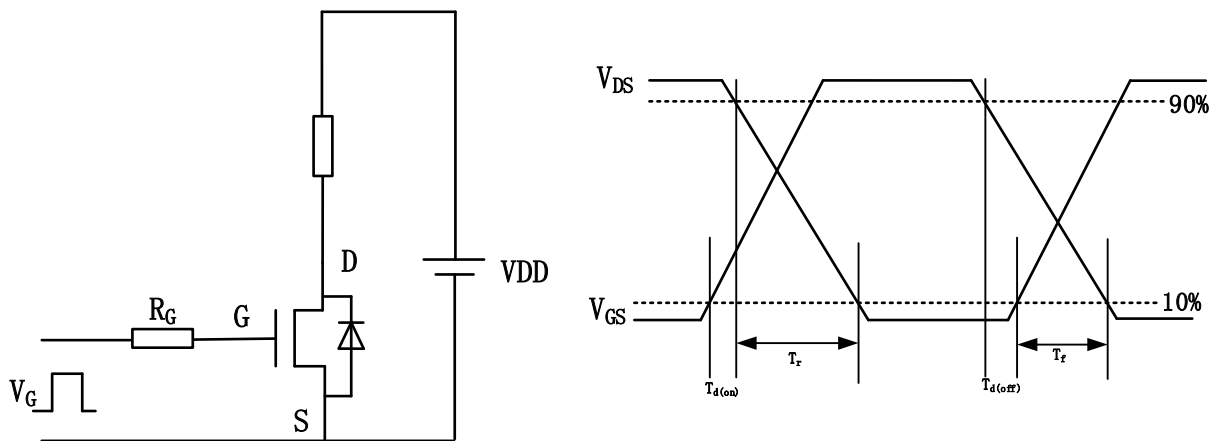


Figure 10 Resistive Switching time Test circuit and waveforms

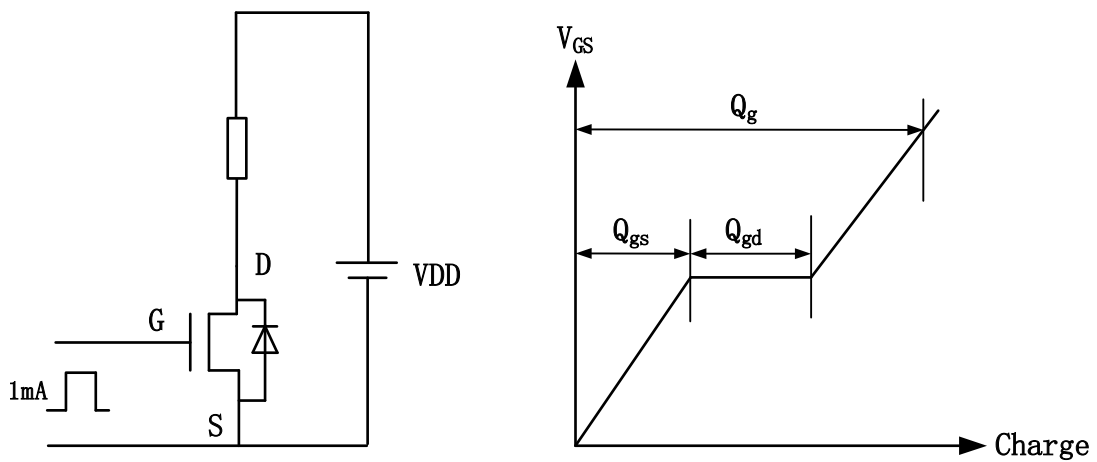
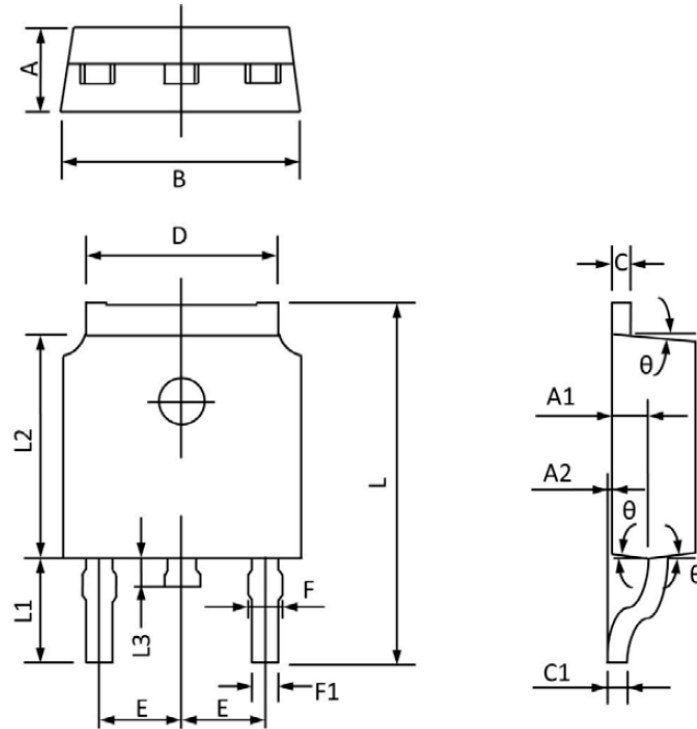


Figure 11 Gate charge Test circuit and waveforms

### Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°